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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	41 × 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.209", 5.30mm Width)
Supplier Device Package	8-SOIJ
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12c509t-04e-sm

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

2.0 PIC12C5XX DEVICE VARIETIES

A variety of packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in this section. When placing orders, please use the PIC12C5XX Product Identification System at the back of this data sheet to specify the correct part number.

2.1 UV Erasable Devices

The UV erasable version, offered in ceramic side brazed package, is optimal for prototype development and pilot programs.

The UV erasable version can be erased and reprogrammed to any of the configuration modes.

Note: Please note that erasing the device will also erase the pre-programmed internal calibration value for the internal oscillator. The calibration value must be saved prior to erasing the part.

Microchip's PICSTART[®] PLUS and PRO MATE[®] programmers all support programming of the PIC12C5XX. Third party programmers also are available; refer to the *Microchip Third Party Guide* for a list of sources.

2.2 <u>One-Time-Programmable (OTP)</u> <u>Devices</u>

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates or small volume applications.

The OTP devices, packaged in plastic packages permit the user to program them once. In addition to the program memory, the configuration bits must also be programmed.

2.3 <u>Quick-Turnaround-Production (QTP)</u> <u>Devices</u>

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and fuse options already programmed by the factory. Certain code and prototype verification procedures do apply before production shipments are available. Please contact your local Microchip Technology sales office for more details.

2.4 <u>Serialized Quick-Turnaround</u> <u>Production (SQTPSM) Devices</u>

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password or ID number.

2.5 Read Only Memory (ROM) Device

Microchip offers masked ROM to give the customer a low cost option for high volume, mature products.

PIC12C5XX

NOTES:

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC12C5XX family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC12C5XX uses a Harvard architecture in which program and data are accessed on separate buses. This improves bandwidth over traditional von Neumann architecture where program and data are fetched on the same bus. Separating program and data memory further allows instructions to be sized differently than the 8-bit wide data word. Instruction opcodes are 12-bits wide making it possible to have all single word instructions. A 12-bit wide program memory access bus fetches a 12-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions. Consequently, all instructions (33) execute in a single cycle (1µs @ 4MHz) except for program branches.

The table below lists program memory (EPROM), data memory (RAM), ROM memory, and non-volatile (EEPROM) for each device.

	Memory									
Device	EPROM Program	ROM Program	RAM Data	EEPROM Data						
PIC12C508	512 x 12		25							
PIC12C509	1024 x 12		41							
PIC12C508A	512 x 12		25							
PIC12C509A	1024 x 12		41							
PIC12CR509A		1024 x 12	41							
PIC12CE518	512 x 12		25 x 8	16 x 8						
PIC12CE519	1024 x 12		41 x 8	16 x 8						

The PIC12C5XX can directly or indirectly address its register files and data memory. All special function registers including the program counter are mapped in the data memory. The PIC12C5XX has a highly orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC12C5XX simple yet efficient. In addition, the learning curve is reduced significantly.

The PIC12C5XX device contains an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The ALU is 8-bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the W (working) register. The other operand is either a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a borrow and digit borrow out bit, respectively, in subtraction. See the SUBWF and ADDWF instructions for examples.

A simplified block diagram is shown in Figure 3-1, with the corresponding device pins described in Table 3-1.

4.3 STATUS Register

This register contains the arithmetic status of the ALU, the RESET status, and the page preselect bit for program memories larger than 512 words.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the TO and PD bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper three bits and set the Z bit. This leaves the STATUS register as 000u uluu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF and MOVWF instructions be used to alter the STATUS register because these instructions do not affect the Z, DC or C bits from the STATUS register. For other instructions, which do affect STATUS bits, see Instruction Set Summary.

FIGURE 4-4: STATUS REGISTER (ADDRESS:03h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x				
GPWUF	—	PA0	TO	PD	Z	DC	С	R = Readable bit			
bit7	6	5	4	3	2	1	bit0	W = Writable bit - n = Value at POR reset			
bit 7:	GPWUF: GPIO reset bit 1 = Reset due to wake-up from SLEEP on pin change 0 = After power up or other reset										
bit 6:	Unimplem	ented									
bit 5:	PA0: Progr 1 = Page 1 0 = Page 0 Each page Using the F page prese	am page p (200h - 3F (000h - 1F is 512 byte PA0 bit as a elect is not	reselect bit Fh) - PIC1 Fh) - PIC1 es. a general pu recommend	s 2C509, PIC 2C5XX urpose read ded since th	12C509A, Pl /write bit in d is may affect	C12CR509	A and PIC12 th do not use mpatibility wi	2CE519 e it for program ith future products.			
bit 4:	TO: Time-out bit 1 = After power-up, CLRWDT instruction, or SLEEP instruction 0 = A WDT time-out occurred										
bit 3:	PD : Power- 1 = After po 0 = By exect	-down bit ower-up or cution of th	by the CLR e SLEEP in	WDT instruc struction	tion						
bit 2:	Z : Zero bit 1 = The res $0 = The res$	sult of an a sult of an a	rithmetic or rithmetic or	logic opera	tion is zero tion is not ze	ero					
bit 1:	DC: Digit carry/borrow bit (for ADDWF and SUBWF instructions) ADDWF 1 = A carry from the 4th low order bit of the result occurred 0 = A carry from the 4th low order bit of the result did not occur SUBWF 1 = A borrow from the 4th low order bit of the result did not occur 0 = A borrow from the 4th low order bit of the result did not occur 0 = A borrow from the 4th low order bit of the result did not occur										
bit 0:	C : Carry/bo ADDWF 1 = A carry 0 = A carry	orrow bit (for r occurred r did not oc	or addwf, s cur	UBWF and R SUBWF 1 = A bor 0 = A bor	RF, RLF insti row did not c row occurred	ructions) occur	RRF or R Load bit w	LF /ith LSB or MSB, respectively			

4.4 OPTION Register

The OPTION register is a 8-bit wide, write-only register which contains various control bits to configure the Timer0/WDT prescaler and Timer0.

By executing the OPTION instruction, the contents of the W register will be transferred to the OPTION register. A RESET sets the OPTION<7:0> bits.

FIGURE 4-5: OPTION REGISTER

Note: If TRIS bit is set to '0', the wake-up on change and pull-up functions are disabled for that pin; i.e., note that TRIS overrides OPTION control of GPPU and GPWU.

Note: If the TOCS bit is set to '1', GP2 is forced to be an input even if TRIS GP2 = '0'.

W-1	W-1	W-1	W-1	W-1	W-1	W-1	W-1				
GPWU	GPPU	TOCS	T0SE	PSA	PS2	PS1	PS0	W = Writable bit			
bit7	6	5	4	3	2	1	bit0	U = Unimplemented bit - n = Value at POR reset Reference Table 4-1 for other resets.			
bit 7:	7: GPWU: Enable wake-up on pin change (GP0, GP1, GP3) 1 = Disabled 0 = Enabled										
bit 6:	GPPU : Ena 1 = Disable 0 = Enable	ble weak p d I	ull-ups (GF	90, GP1, GI	P3)						
bit 5:	T0CS : Timer0 clock source select bit 1 = Transition on T0CKI pin 0 = Transition on internal instruction cycle clock, Fosc/4										
bit 4:	TOSE : Timer0 source edge select bit 1 = Increment on high to low transition on the T0CKI pin 0 = Increment on low to high transition on the T0CKI pin										
bit 3:	PSA : Presc 1 = Prescale 0 = Prescale	aler assigr er assigned er assigned	ment bit d to the WE d to Timer0	DT							
bit 2-0:	PS2:PS0: P	rescaler ra	ate select b	its							
	Bit Value	Timer0 F	Rate WD1	Rate							
	000 001 010 011 100 101 110 111	1:2 1:4 1:8 1:16 1:32 1:64 1:12	1 : 1 : 1 : 1 : 1 : 1 : 1 : 1 :	1 2 4 8 16 32 64 128							

PIC12C5XX

NOTES:



FIGURE 6-2: TIMER0 TIMING: INTERNAL CLOCK/NO PRESCALE

FIGURE 6-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2



TABLE 6-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on All Other Resets
01h	TMR0	Timer0 -	Timer0 - 8-bit real-time clock/counter								uuuu uuuu
N/A	OPTION	GPWU	GPPU	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
N/A	TRIS	_	—	GP5	GP4	GP3	GP2	GP1	GP0	11 1111	11 1111

Legend: Shaded cells not used by Timer0, - = unimplemented, x = unknown, u = unchanged,

FIGURE 7-3: DATA TRANSFER SEQUENCE ON THE SERIAL BUS





7.2 Device Addressing

After generating a START condition, the bus master transmits a control byte consisting of a slave address and a Read/Write bit that indicates what type of operation is to be performed. The slave address consists of a 4-bit device code (1010) followed by three don't care bits.

The last bit of the control byte determines the operation to be performed. When set to a one a read operation is selected, and when set to a zero a write operation is selected. (Figure 7-5). The bus is monitored for its corresponding slave address all the time. It generates an acknowledge bit if the slave address was true and it is not in a programming mode.

FIGURE 7-5: CONTROL BYTE FORMAT



8.2.5 INTERNAL 4 MHz RC OSCILLATOR

The internal RC oscillator provides a fixed 4 MHz (nominal) system clock at VDD = 5V and 25°C, see "Electrical Specifications" section for information on variation over voltage and temperature.

In addition, a calibration instruction is programmed into the top of memory which contains the calibration value for the internal RC oscillator. This location is never code protected regardless of the code protect settings. This value is programmed as a MOVLW XX instruction where XX is the calibration value, and is placed at the reset vector. This will load the W register with the calibration value upon reset and the PC will then roll over to the users program at address 0x000. The user then has the option of writing the value to the OSCCAL Register (05h) or ignoring it.

OSCCAL, when written to with the calibration value, will "trim" the internal oscillator to remove process variation from the oscillator frequency.

Note: Please note that erasing the device will also erase the pre-programmed internal calibration value for the internal oscillator. The calibration value must be read prior to erasing the part. so it can be reprogrammed correctly later.

For the PIC12C508A, PIC12C509A, PIC12CE518, PIC12CE519, and PIC12CR509A, bits <7:2>, CAL5-CAL0 are used for calibration. Adjusting CAL5-0 from 000000 to 111111 yields a higher clock speed. Note that bits 1 and 0 of OSCCAL are unimplemented and should be written as 0 when modifying OSCCAL for compatibility with future devices.

For the PIC12C508 and PIC12C509, the upper 4 bits of the register are used. Writing a larger value in this location yields a higher clock speed.

8.3 <u>RESET</u>

The device differentiates between various kinds of reset:

- a) Power on reset (POR)
- b) MCLR reset during normal operation
- c) MCLR reset during SLEEP
- d) WDT time-out reset during normal operation
- e) WDT time-out reset during SLEEP
- f) Wake-up from SLEEP on pin change

Some registers are not reset in any way; they are unknown on POR and unchanged in any other reset. Most other registers are reset to "reset state" on poweron reset (POR), \overline{MCLR} , WDT or wake-up on pin change reset during normal operation. They are not affected by a WDT reset during SLEEP or \overline{MCLR} reset during SLEEP, since these resets are viewed as resumption of normal operation. The exceptions to this are \overline{TO} , \overline{PD} , and GPWUF bits. They are set or cleared differently in different reset situations. These bits are used in software to determine the nature of reset. See Table 8-3 for a full description of reset states of all registers.

8.6.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). If a longer time-out period is desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT (under software control) by writing to the OPTION register. Thus, a time-out period of a nominal 2.3 seconds can be realized. These periods vary with temperature, VDD and part-to-part process variations (see DC specs).

Under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler), it may take several seconds before a WDT time-out occurs.

8.6.2 WDT PROGRAMMING CONSIDERATIONS

The CLRWDT instruction clears the WDT and the postscaler, if assigned to the WDT, and prevents it from timing out and generating a device RESET.

The SLEEP instruction resets the WDT and the postscaler, if assigned to the WDT. This gives the maximum SLEEP time before a WDT wake-up reset.



FIGURE 8-12: WATCHDOG TIMER BLOCK DIAGRAM

TABLE 8-6: SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on All Other Resets
N/A	OPTION	GPWU	GPPU	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: Shaded boxes = Not used by Watchdog Timer, - = unimplemented, read as '0', u = unchanged

10.0 DEVELOPMENT SUPPORT

10.1 <u>Development Tools</u>

The PICmicro[®] microcontrollers are supported with a full range of hardware and software development tools:

- MPLAB[™]-ICE Real-Time In-Circuit Emulator
- ICEPIC[™] Low-Cost PIC16C5X and PIC16CXXX In-Circuit Emulator
- PRO MATE[®] II Universal Programmer
- PICSTART[®] Plus Entry-Level Prototype Programmer
- SIMICE
- PICDEM-1 Low-Cost Demonstration Board
- PICDEM-2 Low-Cost Demonstration Board
- PICDEM-3 Low-Cost Demonstration Board
- MPASM Assembler
- MPLAB[™] SIM Software Simulator
- MPLAB-C17 (C Compiler)
- Fuzzy Logic Development System (*fuzzy*TECH[®]–MP)
- KEELOQ[®] Evaluation Kits and Programmer

10.2 MPLAB-ICE: High Performance Universal In-Circuit Emulator with MPLAB IDE

The MPLAB-ICE Universal In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PICmicro[®] microcontrollers (MCUs). MPLAB-ICE is supplied with the MPLAB Integrated Development Environment (IDE), which allows editing, "make" and download, and source debugging from a single environment.

Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB-ICE allows expansion to support all new Microchip microcontrollers.

The MPLAB-ICE Emulator System has been designed as a real-time emulation system with advanced features that are generally found on more expensive development tools. The PC compatible 386 (and higher) machine platform and Microsoft Windows[®] 3.x or Windows 95 environment were chosen to best make these features available to you, the end user.

MPLAB-ICE is available in two versions. MPLAB-ICE 1000 is a basic, low-cost emulator system with simple trace capabilities. It shares processor modules with the MPLAB-ICE 2000. This is a full-featured emulator system with enhanced trace, trigger, and data monitoring features. Both systems will operate across the entire operating speed range of the PICmicro[®] MCU.

10.3 ICEPIC: Low-Cost PICmicro[®] In-Circuit Emulator

ICEPIC is a low-cost in-circuit emulator solution for the Microchip PIC12CXXX, PIC16C5X and PIC16CXXX families of 8-bit OTP microcontrollers.

ICEPIC is designed to operate on PC-compatible machines ranging from 386 through Pentium[™] based machines under Windows 3.x, Windows 95, or Windows NT environment. ICEPIC features real time, non-intrusive emulation.

10.4 PRO MATE II: Universal Programmer

The PRO MATE II Universal Programmer is a full-featured programmer capable of operating in stand-alone mode as well as PC-hosted mode. PRO MATE II is CE compliant.

The PRO MATE II has programmable VDD and VPP supplies which allows it to verify programmed memory at VDD min and VDD max for maximum reliability. It has an LCD display for displaying error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In standalone mode the PRO MATE II can read, verify or program PIC12CXXX, PIC14C000, PIC16C5X, PIC16CXXX and PIC17CXX devices. It can also set configuration and code-protect bits in this mode.

10.5 <u>PICSTART Plus Entry Level</u> <u>Development System</u>

The PICSTART programmer is an easy-to-use, lowcost prototype programmer. It connects to the PC via one of the COM (RS-232) ports. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. PICSTART Plus is not recommended for production programming.

PICSTART Plus supports all PIC12CXXX, PIC14C000, PIC16C5X, PIC16CXXX and PIC17CXX devices with up to 40 pins. Larger pin count devices such as the PIC16C923, PIC16C924 and PIC17C756 may be supported with an adapter socket. PICSTART Plus is CE compliant.

10.10 <u>MPLAB Integrated Development</u> <u>Environment Software</u>

The MPLAB IDE Software brings an ease of software development previously unseen in the 8-bit microcontroller market. MPLAB is a windows based application which contains:

- A full featured editor
- Three operating modes
 - editor
 - emulator
 - simulator
- A project manager
- Customizable tool bar and key mapping
- A status bar with project information
- · Extensive on-line help

MPLAB allows you to:

- Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PICmicro[®] tools (automatically updates all project information)
- Debug using:
- source files
- absolute listing file

The ability to use MPLAB with Microchip's simulator allows a consistent platform and the ability to easily switch from the low cost simulator to the full featured emulator with minimal retraining due to development tools.

10.11 Assembler (MPASM)

The MPASM Universal Macro Assembler is a PChosted symbolic assembler. It supports all microcontroller series including the PIC12C5XX, PIC14000, PIC16C5X, PIC16CXXX, and PIC17CXX families.

MPASM offers full featured Macro capabilities, conditional assembly, and several source and listing formats. It generates various object code formats to support Microchip's development tools as well as third party programmers.

MPASM allows full symbolic debugging from MPLAB-ICE, Microchip's Universal Emulator System.

MPASM has the following features to assist in developing software for specific use applications.

- Provides translation of Assembler source code to object code for all Microchip microcontrollers.
- Macro assembly capability.
- Produces all the files (Object, Listing, Symbol, and special) required for symbolic debug with Microchip's emulator systems.
- Supports Hex (default), Decimal and Octal source and listing formats.

MPASM provides a rich directive language to support programming of the PICmicro[®]. Directives are helpful in making the development of your assemble source code shorter and more maintainable.

10.12 Software Simulator (MPLAB-SIM)

The MPLAB-SIM Software Simulator allows code development in a PC host environment. It allows the user to simulate the PICmicro[®] series microcontrollers on an instruction level. On any given instruction, the user may examine or modify any of the data areas or provide external stimulus to any of the pins. The input/ output radix can be set by the user and the execution can be performed in; single step, execute until break, or in a trace mode.

MPLAB-SIM fully supports symbolic debugging using MPLAB-C17 and MPASM. The Software Simulator offers the low cost flexibility to develop and debug code outside of the laboratory environment making it an excellent multi-project software development tool.

10.13 MPLAB-C17 Compiler

The MPLAB-C17 Code Development System is a complete ANSI 'C' compiler and integrated development environment for Microchip's PIC17CXXX family of microcontrollers. The compiler provides powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compiler provides symbol information that is compatible with the MPLAB IDE memory display.

10.14 <u>Fuzzy Logic Development System</u> (fuzzyTECH-MP)

*fuzzy*TECH-MP fuzzy logic development tool is available in two versions - a low cost introductory version, MP Explorer, for designers to gain a comprehensive working knowledge of fuzzy logic system design; and a full-featured version, *fuzzy*TECH-MP, Edition for implementing more complex systems.

Both versions include Microchip's *fuzzy*LAB[™] demonstration board for hands-on experience with fuzzy logic systems implementation.

10.15 <u>SEEVAL® Evaluation and</u> <u>Programming System</u>

The SEEVAL SEEPROM Designer's Kit supports all Microchip 2-wire and 3-wire Serial EEPROMs. The kit includes everything necessary to read, write, erase or program special features of any Microchip SEEPROM product including Smart Serials[™] and secure serials. The Total Endurance[™] Disk is included to aid in trade-off analysis and reliability calculations. The total kit can significantly reduce time-to-market and result in an optimized system.

11.1 DC CHARACTERISTICS:

PIC12C508/509 (Commercial, Industrial, Extended)

	DC Characteristics Power Supply Pins		Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \leq TA \leq +70^{\circ}C$ (commercial) $-40^{\circ}C \leq TA \leq +85^{\circ}C$ (industrial) $-40^{\circ}C \leq TA \leq +125^{\circ}C$ (extended)						
Parm No.	Characteristic	Sym	Min	Typ ⁽¹⁾	Max	Units	Conditions		
D001	Supply Voltage	Vdd	2.5 3.0		5.5 5.5	V V	Fosc = DC to 4 MHz (Commercial/ Industrial) Fosc = DC to 4 MHz (Extended)		
D002	RAM Data Retention Voltage ⁽²⁾	Vdr		1.5*		V	Device in SLEEP mode		
D003	VDD Start Voltage to ensure Power-on Reset	VPOR		Vss		V	See section on Power-on Reset for details		
D004	VDD Rise Rate to ensure Power-on Reset	SVDD	0.05 *			V/ms	See section on Power-on Reset for details		
D010	Supply Current ⁽³⁾	Idd	_	.78	2.4	mA	XT and EXTRC options ⁽⁴⁾ Fosc = 4 MHz, VDD = 5.5V		
D010C			—	1.1	2.4	mA	INTRC Option Fosc = 4 MHz, VDD = 5.5V		
D010A			—	10	27	μA	LP OPTION, Commercial Temperature Fosc = 32 kHz, VDD = 3.0V, WDT disabled		
			—	14	35	μA	LP OPTION, Industrial Temperature Fosc = 32 kHz, VDD = 3.0V, WDT disabled		
				14	35	μA	LP OPTION, Extended Temperature FOSC = 32 kHz, VDD = 3.0V, WDT disabled		
D020 D021 D021B	Power-Down Current ⁽⁵⁾	IPD		0.25 0.25 2	4 5 18	μΑ μΑ μΑ	VDD = 3.0V, Commercial WDT disabled VDD = 3.0V, Industrial WDT disabled VDD = 3.0V, Extended WDT disabled		
D022		ΔİWDT		3.75 3.75 3.75	8 9 14	μΑ μΑ μΑ	VDD = 3.0V, Commercial VDD = 3.0V, Industrial VDD = 3.0V, Extended		

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

- 2: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
- 3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active operation mode are:
 - OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to V_{ss} , T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode.
- 4: Does not include current through Rext. The current through the resistor can be estimated by the formula: IR = VDD/2Rext (mA) with Rext in kOhm.
- 5: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

11.2 DC CHARACTERISTICS:

PIC12C508/509 (Commercial, Industrial, Extended)

		Standard Operating Conditions (unless otherwise specified)							
		Operati	ng tempera	ture	0°C ≤	$TA \leq +$	70°C (commercial)		
					$−40^{\circ}C ≤$	TA ≤ +8	35°C (industrial)		
DC CII/	RACIERISTICS				−40°C ≤	TA ≤ +1	25°C (extended)		
		Operating voltage VDD range as described in DC spec Section 11.1 and							
		Section	11.2.						
Param	Characteristic	Sym	Min	Typ†	Max	Units	Conditions		
No.									
	Input Low Voltage								
	I/O ports	VIL		-					
D030	with TTL buffer		Vss	-	0.8V	V	$4.5 < VDD \le 5.5V$		
				-	0.15Vdd	V	otherwise		
D031	with Schmitt Trigger buffer		Vss	-	0.15Vdd	V			
D032	MCLR, GP2/T0CKI (in EXTRC mode)		Vss	-	0.15Vdd	V			
D033	OSC1 (EXTRC) (1)		Vss	-	0.15Vdd				
D033	OSC1 (in XT and LP)		Vss	-	0.3Vpp	V	Note1		
	Input High Voltage					-			
	I/O ports	Vін		-					
D040	with TTL buffer	Vss	2.01/	-	Voo	V	4 5 < Vod < 5 5V		
D040A		100	0 25Vpp+	-	VDD	v	otherwise		
2010/1			0.8V		100	•			
D041	with Schmitt Trigger buffer		0.85VDD	-	VDD	V	For entire VDD range		
D042	MCLR/GP2/T0CKI		0.85VDD	-	Vdd	V	5		
D042A	OSC1 (XT and LP)		0.7VDD	-	VDD	V	Note1		
D043	OSC1 (in EXTRC mode)		0.85VDD	-	Vdd	V			
D070	GPIO weak pull-up current	IPUR	50	250	400	μA	VDD = 5V, VPIN = VSS		
	Input Leakage Current ^(2, 3)					•	For VDD ≤5.5V		
D060	I/O ports	In	-1	0.5	+1	μА	Vss < VPIN < VDD		
			-		<u> </u>	P	Pin at hi-impedance		
D061	MCLR, GP2/T0CKI		20	130	250	μA	$V_{PIN} = V_{SS} + 0.25 V(2)$		
				0.5	+5	μA	VPIN = VDD		
D063	OSC1		-3	0.5	+3	uА	Vss < VPIN < VDD.		
			-			P	XT and LP options		
	Output Low Voltage								
D080	I/O ports/CLKOUT	Vol	-	-	0.6	V	IOL = 8.7 mA, VDD = 4.5V		
	Output High Voltage								
D090	I/O ports/CLKOUT (3)	Voн	Vdd - 0.7	-	-	V	IOH = -5.4 mA, VDD = 4.5V		
	Capacitive Loading Specs on								
	Output Pins								
D100	OSC2 pin	Cosc2	-	-	15	pF	In XT and LP modes when		
							external clock is used to drive		
							OSC1.		
D101	All I/O pins	Cio	-	-	50	pF			

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In EXTRC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC12C5XX be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

TABLE 11-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC12C508/C509

AC Charac	teristics	$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq T_A \leq +70^{\circ}C \mbox{ (commercial)} \\ & -40^{\circ}C \leq T_A \leq +85^{\circ}C \mbox{ (industrial)} \\ & -40^{\circ}C \leq T_A \leq +125^{\circ}C \mbox{ (extended)} \\ \mbox{Operating Voltage VDD range is described in Section 11.1} \end{array} $						
Parameter No.	Sym	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions	
30	TmcL	MCLR Pulse Width (low)	2000*	—	—	ns	VDD = 5 V	
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9*	18*	30*	ms	VDD = 5 V (Commercial)	
32	TDRT	Device Reset Timer Period ⁽²⁾	9*	18*	30*	ms	VDD = 5 V (Commercial)	
34	Tioz	I/O Hi-impedance from MCLR Low	_	_	2000*	ns		

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 2: See Table 11-6.

TABLE 11-6: DRT (DEVICE RESET TIMER PERIOD - PIC12C508/C509)

Oscillator Configuration	POR Reset	Subsequent Resets		
IntRC & ExtRC	18 ms (typical)	300 µs (typical)		
XT & LP	18 ms (typical)	18 ms (typical)		

FIGURE 11-5: TIMER0 CLOCK TIMINGS - PIC12C508/C509



TABLE 11-7: TIMER0 CLOCK REQUIREMENTS - PIC12C508/C509

AC	Chara	cteristics	$\label{eq:conditions} \begin{array}{l} \mbox{(unless otherwise specified)} \\ \mbox{iture} & 0^\circ C \leq T A \leq +70^\circ C \mbox{ (commercial)} \\ & -40^\circ C \leq T A \leq +85^\circ C \mbox{ (industrial)} \\ & -40^\circ C \leq T A \leq +125^\circ C \mbox{ (extended)} \\ \mbox{VDD range is described in Section 11.1.} \end{array}$					
Parameter No.	Sym	Characteristic	Min	Тур ⁽¹⁾	Мах	Units	Conditions	
40	Tt0H	T0CKI High Pulse V	Vidth - No Prescaler	0.5 TCY + 20*	—	_	ns	
			- With Prescaler	10*	—		ns	
41	Tt0L	T0CKI Low Pulse W	/idth - No Prescaler	0.5 TCY + 20*	_		ns	
			- With Prescaler	10*	_	-	ns	
42	42 Tt0P T0CKI Period				—		ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Oscillator	Frequency	VDD = 2.5V	VDD = 5.5V
External RC	4 MHz	250 µA*	780 µA*
Internal RC	4 MHz	420 µA	1.1 mA
ХТ	4 MHz	251 µA	780 µA
LP	32 KHz	15 µA	37 µA

TABLE 12-1: DYNAMIC IDD (TYPICAL) - WDT ENABLED, 25°C

*Does not include current through external R&C.



FIGURE 12-3: WDT TIMER TIME-OUT PERIOD VS. VDD

FIGURE 12-4: SHORT DRT PERIOD VS. VDD



13.2 DC CHARACTERISTICS:

PIC12LC508A/509A (Commercial, Industrial) PIC12LCE518/519 (Commercial, Industrial) PIC12LCR509A (Commercial, Industrial)

DC Characteristics Power Supply Pins				$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ (commercial)} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ (industrial)} \end{array}$							
Parm No.	Characteristic	Sym	Min	Typ ⁽¹⁾	Max	Units	Conditions				
D001	Supply Voltage	Vdd	2.5		5.5	V	Fosc = DC to 4 MHz (Commercial/ Industrial)				
D002	RAM Data Retention Voltage ⁽²⁾	Vdr		1.5*		V	Device in SLEEP mode				
D003	VDD Start Voltage to ensure Power-on Reset	VPOR		Vss		V	See section on Power-on Reset for details				
D004	VDD Rise Rate to ensure Power-on Reset	SVDD	0.05*			V/ms	See section on Power-on Reset for details				
D010	Supply Current ⁽³⁾	IDD	—	0.4	0.8	mA	XT and EXTRC options (Note 4) Fosc = 4 MHz, VDD = 2.5V				
D010C			—	0.4	0.8	mA	INTRC Option Fosc = 4 MHz, VDD = 2.5V				
D010A			—	15	23	μA	LP OPTION, Commercial Temperature FOSC = 32 kHz, VDD = 2.5V, WDT disabled				
			_	15	31	μA	LP OPTION, Industrial Temperature Fosc = 32 kHz, VDD = 2.5V, WDT disabled				
D020	Power-Down Current ⁽⁵⁾	IPD			_	_					
D021 D021B				0.2 0.2	3 4	μΑ μΑ	VDD = 2.5V, Commercial VDD = 2.5V, Industrial				
		Δ IWDT	—	2.0 2.0	4 5	mA mA	VDD = 2.5V, Commercial VDD = 2.5V, Industrial				

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

- 2: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
- 3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode.
- 4: Does not include current through Rext. The current through the resistor can be estimated by the formula: IR = VDD/2Rext (mA) with Rext in kOhm.
- 5: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.

13.4 DC CHARACTERISTICS:

PIC12LC508A/509A (Commercial, Industrial) PIC12LC518/519 (Commercial, Industrial) PIC12LCR509A (Commercial, Industrial)

		Standard Operating Conditions (unless otherwise specified)										
			Operating temperature $0^{\circ}C \le TA \le +70^{\circ}C$ (commercial)									
DC CHARACTERISTICS			$-40^{\circ}C \le TA \le +85^{\circ}C$ (industrial)									
			Operating voltage VDD range as described in DC spec Section 13.1 and									
_	Section 13.2.											
Param	Characteristic	Sym	Min	Тур†	Max	Units	Conditions					
NO.												
	Input Low Voltage											
	I/O ports	VIL										
D030	with TTL buffer		Vss	-	0.8V	V	For $4.5V \le VDD \le 5.5V$					
			Vss	-	0.15Vdd	V	otherwise					
D031	with Schmitt Trigger buffer		Vss	-	0.2Vdd	V						
D032	MCLR, GP2/T0CKI (in EXTRC mode)		Vss	-	0.2Vdd	V						
D033	OSC1 (in EXTRC mode)		Vss	-	0.2Vdd	V	Note 1					
D033	OSC1 (in XT and LP)		Vss	-	0.3Vdd	V	Note 1					
	Input High Voltage											
	I/O ports	Vін		-								
D040	with TTL buffer		0.25VDD +	-	Vdd	V	$4.5V \le VDD \le 5.5V$					
			0.8V									
D040A			2.0V	-	Vdd	V	otherwise					
D041	with Schmitt Trigger buffer		0.8Vdd	-	Vdd	V	For entire VDD range					
D042	MCLR, GP2/T0CKI		0.8Vdd	-	Vdd	V						
D042A	OSC1 (XT and LP)		0.7Vdd	-	Vdd	V	Note 1					
D043	OSC1 (in EXTRC mode)		0.9Vdd	-	Vdd	V						
D070	GPIO weak pull-up current (Note 4)	IPUR	30	250	400	μΑ	VDD = 5V, VPIN = VSS					
	MCLR pull-up current	-	-	-	30	μΑ	VDD = 5V, VPIN = VSS					
	Input Leakage Current (Notes 2, 3)											
D060	I/O ports	lı∟	-	-	<u>+</u> 1	μA	Vss \leq VPIN \leq VDD, Pin at hi-imped-					
							ance					
D061	TOCKI		-	-	<u>+</u> 5	μΑ	$Vss \le Vpin \le Vdd$					
D063	OSC1		-	-	<u>+</u> 5	μΑ	$Vss \leq VPIN \leq VDD$, XT and LP osc					
							configuration					
	Output Low Voltage											
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V,					
							–40°C to +85°C					
D080A			-	-	0.6	V	IOL = 7.0 mA, VDD = 4.5 V,					
							–40°C to +125°C					
_	Output High Voltage											
D090	I/O ports (Note 3)	Voн	Vdd - 0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5 V,					
							-40°C to +85°C					
D090A			VDD - 0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5 V,					
							-40°C to +125°C					
	Capacitive Loading Specs on											
D100	OSC2 pin	റററ			15	n⊑	In XT and I P modes when exter					
0100		2	-	-	15	μr	nal clock is used to drive OSC1					
D101	All I/O pins	Cio	-	_	50	nЕ	That block is used to unive OSCI.					
		00	-	-	50	P						

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In EXTRC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC12C5XX be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: This spec. applies when GP3/MCLR is configured as MCLR. The leakage current of the MCLR circuit is higher than the standard I/O logic.





FIGURE 14-13: TYPICAL IPD VS. VDD, WATCHDOG DISABLED (25°C)